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With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

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# 12 V, 1 A, Low V<sub>CE(sat)</sub> PNP Transistor

ON Semiconductor's e²PowerEdge family of low  $V_{CE(sat)}$  transistors are miniature surface mount devices featuring ultra low saturation voltage ( $V_{CE(sat)}$ ) and high current gain capability. These are designed for use in low voltage, high speed switching applications where affordable efficient energy control is important.

Typical application are DC-DC converters and power management in portable and battery powered products such as cellular and cordless phones, PDAs, computers, printers, digital cameras and MP3 players. Other applications are low voltage motor controls in mass storage products such as disc drives and tape drives. In the automotive industry they can be used in air bag deployment and in the instrument cluster. The high current gain allows e<sup>2</sup>PowerEdge devices to be driven directly from PMU's control outputs, and the Linear Gain (Beta) makes them ideal components in analog amplifiers.

### **Features**

- High Continuous Current Capability (1 A)
- Low V<sub>CE(sat)</sub> (150 mV Typical @ 500 mA)
- Small Size 1.2 mm x 1.2 mm
- This is a Pb-Free Device

#### **Benefits**

- High Specific Current and Power Capability Reduces Required PCB Area
- Reduced Parasitic Losses Increases Battery Life

### MAXIMUM RATINGS (T<sub>A</sub> = 25°C)

Rating	Symbol	Max	Unit
Collector-Emitter Voltage	V <sub>CEO</sub>	-12	Vdc
Collector-Base Voltage	V <sub>CBO</sub>	-12	Vdc
Emitter-Base Voltage	V <sub>EBO</sub>	-5.0	Vdc
Collector Current - Continuous - Peak	I <sub>C</sub> I <sub>CM</sub>	-1.0 -3.0	Adc
Electrostatic Discharge	ESD	HBM Class 3B MM Class C	

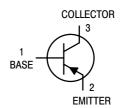
Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.



# ON Semiconductor®

http://onsemi.com

# 12 VOLTS, 1.0 AMPS PNP LOW $V_{CE(sat)}$ TRANSISTOR EQUIVALENT $R_{DS(on)}$ 350 m $\Omega$



MARKING DIAGRAM



SOT-723 CASE 631AA STYLE 1



VE = Specific Device Code M = Date Code

#### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
NSS12100M3T5G	SOT-723 (Pb-Free)	8000/ Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

# THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation T <sub>A</sub> = 25°C	P <sub>D</sub> (Note 1)	460	mW
Derate above 25°C		3.7	mW/°C
Thermal Resistance, Junction-to-Ambient	R <sub>θJA</sub> (Note 1)	270	°C/W
Total Device Dissipation  T <sub>A</sub> = 25°C  Derate above 25°C	P <sub>D</sub> (Note 2)	625 5.0	mW mW/°C
Thermal Resistance, Junction-to-Ambient	R <sub>θJA</sub> (Note 2)	200	°C/W
Thermal Resistance, Junction-to-Lead 3	$R_{ heta JL}$	105	°C/W
Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C

# **ELECTRICAL CHARACTERISTICS** (T<sub>J</sub> = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS					
Collector - Emitter Breakdown Voltage, (I <sub>C</sub> = -10 mAdc, I <sub>B</sub> = 0)	V <sub>(BR)CEO</sub>	-12	-	-	Vdc
Collector - Base Breakdown Voltage, (I <sub>C</sub> = -0.1 mAdc, I <sub>E</sub> = 0)	V <sub>(BR)CBO</sub>	-12	_	-	Vdc
Emitter - Base Breakdown Voltage, (I <sub>E</sub> = -0.1 mAdc, I <sub>C</sub> = 0)	V <sub>(BR)EBO</sub>	-5.0	_	-	Vdc
Collector Cutoff Current, (V <sub>CB</sub> = -12 Vdc, I <sub>E</sub> = 0)	I <sub>CBO</sub>	-	-0.01	-0.1	μAdc
Emitter Cutoff Current, (V <sub>CES</sub> = -5.0 Vdc, I <sub>E</sub> = 0)	I <sub>EBO</sub>	-	-0.01	-0.1	μAdc
ON CHARACTERISTICS					
DC Current Gain (Note 3) ( $I_C = -10$ mA, $V_{CE} = -2.0$ V) ( $I_C = -500$ mA, $V_{CE} = -2.0$ V) ( $I_C = -1.0$ A, $V_{CE} = -2.0$ V)	h <sub>FE</sub>	200 120 80	- - -	- - -	
Collector - Emitter Saturation Voltage (Note 3) $ \begin{aligned} &(I_C = -0.05 \text{ A}, \ I_B = -0.005 \text{ A}) \text{ (Note 4)} \\ &(I_C = -0.1 \text{ A}, \ I_B = -0.002 \text{ A}) \\ &(I_C = -0.1 \text{ A}, \ I_B = -0.010 \text{ A}) \\ &(I_C = -0.5 \text{ A}, \ I_B = -0.050 \text{ A}) \\ &(I_C = -1.0 \text{ A}, \ I_B = -0.100 \text{ A}) \end{aligned} $	V <sub>CE(sat)</sub>	- - - -	-0.030 -0.060 -0.040 -0.155 -0.350	-0.035 -0.080 -0.060 -0.220 -0.410	V
Base – Emitter Saturation Voltage (Note 3) $(I_C = -1.0 \text{ A}, I_B = -0.01 \text{ A})$	V <sub>BE(sat)</sub>	-	0.95	-1.15	V
Base - Emitter Turn-on Voltage (Note 3) (I <sub>C</sub> = -2.0 A, V <sub>CE</sub> = -2.0 V)	V <sub>BE(on)</sub>	-	-1.05	-1.15	V
SMALL-SIGNAL CHARACTERISTICS					
Input Capacitance (V <sub>EB</sub> = −0.5 V, f = 1.0 MHz)	Cibo	_	40	50	pF
Output Capacitance (V <sub>CB</sub> = -3.0 V, f = 1.0 MHz)	Cobo	-	15	20	pF
Noise Figure (I <sub>C</sub> = 0.2 mA, $V_{CF}$ = 5.0 V, $R_{S}$ = 1.0 k $\Omega$ , f = 1.0 MHz, BW = 200 Hz)	NF	_	_	5.0	dB

FR-4 @ 100 mm², 1 oz copper traces.
 FR-4 @ 500 mm², 1 oz copper traces.
 Pulsed Condition: Pulse Width = 300 μsec, Duty Cycle ≤ 2%.
 Guaranteed by design but not tested.

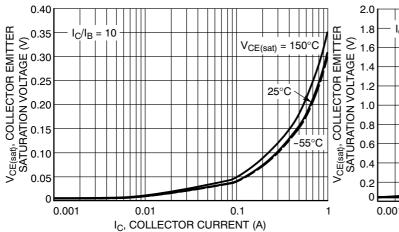


Figure 1. Collector Emitter Saturation Voltage vs.
Collector Current

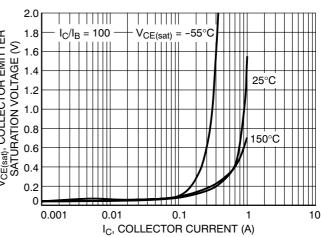


Figure 2. Collector Emitter Saturation Voltage vs.
Collector Current

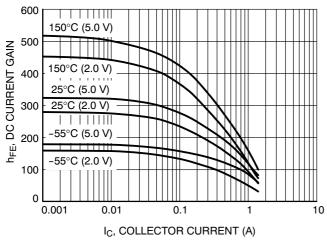


Figure 3. DC Current Gain vs. Collector Current

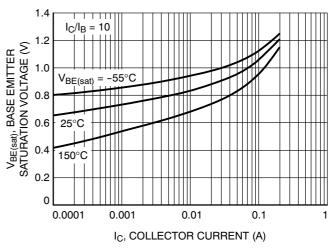


Figure 4. Base Emitter Saturation Voltage vs.
Collector Current

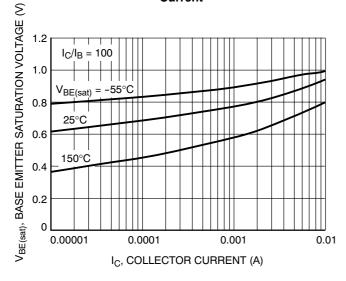


Figure 5. Base Emitter Saturation Voltage vs.
Collector Current

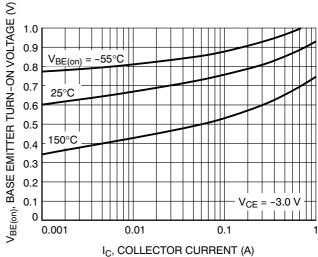
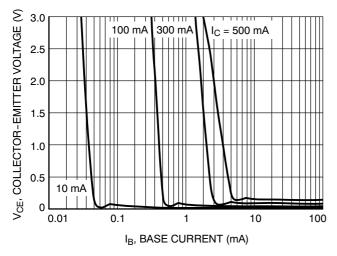


Figure 6. Base Emitter Turn-On Voltage vs.
Collector Current

50



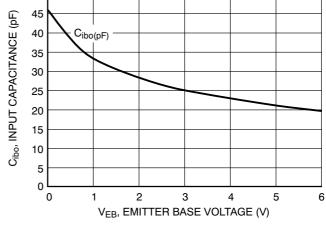
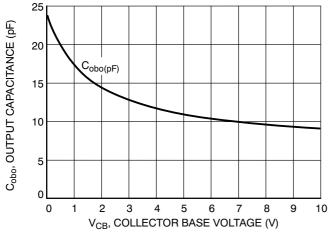


Figure 7. Saturation Region @ 25°C

Figure 8. Input Capacitance



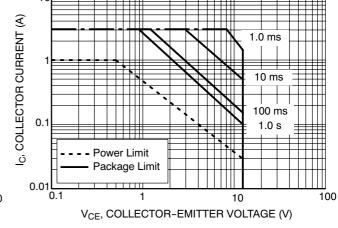
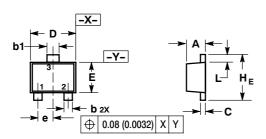


Figure 9. Output Capacitance

Figure 10. Safe Operating Area

#### PACKAGE DIMENSIONS

SOT-723 CASE 631AA-01 **ISSUE C** 



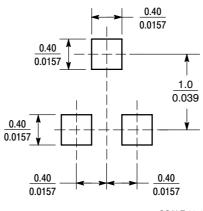
# NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI
- DIMENSIONING AND TOLERANGING FET GROSTY 14.5M, 1982.
  CONTROLLING DIMENSION: MILLIMETERS.
  MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
- DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.

	MILLIMETERS INCHES			;		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.45	0.50	0.55	0.018	0.020	0.022
b	0.15	0.21	0.27	0.0059	0.0083	0.0106
b1	0.25	0.31	0.37	0.010	0.012	0.015
С	0.07	0.12	0.17	0.0028	0.0047	0.0067
D	1.15	1.20	1.25	0.045	0.047	0.049
Е	0.75	0.80	0.85	0.03	0.032	0.034
е	0.40 BSC			0.016 BSC		
ΗE	1.15	1.20	1.25	0.045	0.047	0.049
Ĺ	0.15	0.20	0.25	0.0059	0.0079	0.0098

STYLE 1: PIN 1. BASE 2. EMITTER 3. COLLECTOR

#### **SOLDERING FOOTPRINT\***



SCALE 20:1

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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